As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED, the specification of which (check one):

;							
ı	is attached hereto. was filed on	as United States	application serial no.	and was amende	d on		
	was filed on	as PCT internat	ional application no.	and was amended	under PCT Article 19 c	on	
I her	eby state that I have re to above.	eviewed and understa	and the contents of the above-	-identified specification	, including the claims,	as amended by an	y amendment
I ack	mowledge the duty to	disclose to the U.S. I	Patent and Trademark Office ned in Title 37, Code of Fede	all information known eral Regulations § 1.56.	to me to be material to	the patentability o	f the subject matter
			Title 25 I Inited States Code	8 119(a)-(d) or 8 365(h	) of any foreign applica	tion(s) for patent	or inventor's
certifica attached PCT int	ate or § 365(a) of any	PCT international ap	plication(s) designating at lead below and on any attached ast one country other than the	ast one country other th	foreign application for t	natent or inventor	s certificate or any
Prior fo	reign/PCT application	n(s):				Priority Clai	med
	200103014-7 (number)		Singapore (country)	M (day/r	ay 21, 2001 nonth/year filed)	Yes	No
	(number)		(country) ted States Code, § 120 of any	` '	nonth/year filed)	Yes	No
applica duty to Regula	ation is not disclosed in disclose to the U.S. Futions § 1.56 which be	n any such prior app	elow and on any attached con lication in the manner provid c Office all information know een the filing date of such pri	en by the thist paragrap	o natentability as define	ed in Title 37, Coo tional filing date o	de of Federal f this application:
ap	plication serial no.)		(filing date)				
= (application serial no.)			(filing date)		(status - pending, patented or abandoned)		
i h		t under Title 35, Un	ited States Code, § 119(e) of	any United States provi	sional application(s) lis	sted below:	
74	(provisional application	on no.)	(filing date)				
LI LA h therev	ereby appoint the folk	owing Registered Pra	actitioners to prosecute this ap	pplication and to transa	ct all business in the Pa	tent and Trademan	k Office connected
Jos Al Br Kr Sh	avid V. Trask, Reg. No seph A. Walkowski, R len C. Turner, Reg. N ick G. Power, Reg. N ista Weber Powell, Ro lawn G. Hansen, Reg. atherine A. Hamer, Re	eg. No. 28,765 o. 33,041 o. 38,581 eg. No. 47,867 No. 42,627	William S. Britt, Reg. No. James R. Duzan, Reg. No. Edgar R. Cataxinos, Reg. Paul C. Oestreich, Reg. N. Jarett K. Abramson, Reg. Bretton L. Crockett, Reg. Michael L. Lynch, Reg. N	. 28,393 No. 39,931 Io. 44,983 No. 47,376 No. 44,632	Laurence B. Bond, R H. Dickson Burton, I Kent S. Burningham Devin R. Jensen, Reg David L. Stott, Reg. Bradley B. Jensen, R Charles B. Brantley	Reg. No. P-48,39 , Reg. No. 30,453 g. No. 44,805 No. 43,937 Leg. No. 46,801	
Addre	ess all correspondence	to: Josep TRA: P.O. Salt	oh A. Walkowski, telephone r SKBRITT, PC BOX 2550 Lake City, Utah 84110				
I I furthe Section	nereby declare that all er that these statement on 1001 of Title 18 of	statements made her s were made with the the United States Co	rein of my own knowledge are e knowledge that willful false ode and that such willful false	e true and that all stater statements and the like e statements may jeopar	nents made on informate so made are punishable dize the validity of the	ion and belief are e by fine or impris application or any	believed to be true; an sonment, or both, unde patent issued thereon.
Inver	name of first joint inventor's signature	entor: Chon Chin H	ui	Dat	e		<del></del> -
Resid	lence: Singapore	inganore	yoh #04-100, Singapore 3102				
Full i	name of second joint i	nventor: Lee Kian C	Chai	Dat	e		
Resid	dence: Singapore enship: Republic of S						

Post Office Address: Block 235, Compassvale Walk #06-506, Singapore 540235

## DECLARATION FOR PATENT APPLICAT

(continuation page)

Invention title: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Inventor name(s) appearing on first declaration page: Chon Chin Hui			
Additional original, first and joint inventor(s):			
Full name of third joint inventor: Jason Pittam Inventor's signature Residence: Morgan Hill, California Citizenship: U.S.A. Post Office Address: 16745 Barnell Avenue, Apt. 3, Morgan Hill, California 95037-4922	_ Date	 <u>· ,                                     </u>	

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